



## Material Content Data Sheet



<b>Sales Product Name</b>		ICE3A2565		<b>Issued</b>		27. September 2017		
<b>MA#</b>		MA000981078						
<b>Package</b>		PG-DIP-8-13		<b>Weight*</b>		558.10 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.508	1.52	1.52	15245	15245
leadframe	inorganic material	phosphorus	7723-14-0	0.054	0.01		96	
	non noble metal	zinc	7440-66-6	0.215	0.04		385	
	non noble metal	iron	7439-89-6	4.297	0.77		7699	
wire	non noble metal	copper	7440-50-8	174.475	31.26	32.08	312622	320802
	noble metal	gold	7440-57-5	0.229	0.04	0.04	410	410
	encapsulation	organic material	carbon black	1333-86-4	1.079	0.19		1933
encapsulation	plastics	epoxy resin	-	34.888	6.25		62511	
	inorganic material	silicondioxide	60676-86-0	323.701	58.02	64.46	580003	644447
leadfinish	non noble metal	tin	7440-31-5	7.496	1.34	1.34	13431	13431
plating	noble metal	silver	7440-22-4	0.796	0.14	0.14	1426	1426
glue	plastics	epoxy resin	-	0.355	0.06		636	
	noble metal	silver	7440-22-4	2.011	0.36	0.42	3603	4239
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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